

ABSTRACT

A TRAY FOR A WAFER WITH TAPE FRAME

5 The purpose of the present invention is to provide a tray for reducing swings
and for preventing breakage of semiconductor wafers by vibrations of a
container even when an ultrathin semiconductor wafer with tape frame
having a thickness of 200 μ m or less is transported by being stored in the
container. The tray for use in storing a wafer with tape frame in a storage
10 container, the wafer with tape frame comprises a ring-shaped frame, a dicing
tape and a semiconductor wafer, the dicing tape is stuck on the rear surface of
the ring-shaped frame, the semiconductor wafer is supported on the dicing
tape, wherein, the tray has a substantially circular shape and is positioned on
the upper side and the lower side of the wafer with tape frame; the front
15 surface of the tray has a substantially flat portion for mounting the wafer
with tape frame, at least a portion of the outer peripheral portion of the front
surface of the tray includes a convex portion; and a projecting portion is
formed on the rear surface of the tray so that the projection portion is
positioned outside the outer periphery of the semiconductor wafer of the
20 wafer with tape frame when the tray is positioned on the wafer with tape
frame.

[Fig. 3]